Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!

Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832
Email & Skype: info@chipsmall.com Web: www.chipsmall.com
Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China

NZL5V6AXV3T1 Series

ESD Protection Diode

Dual Common Anode

These dual monolithic silicon ESD protection diodes are intended for use in voltage− and ESD−sensitive equipment such as computers, printers, business machines, communication systems, medical equipment and other applications. Their dual junction common anode design protects two separate lines using only one package. These devices are ideal for situations where board space is at a premium.

Specification Features:

- SC−89 Package Allows Either Two Separate Unidirectional Configurations or a Single Bidirectional Configuration
- ESD Rating of Class N (exceeding 16 kV) per the Human Body Model
- Meets IEC61000−4−2 Level 4
- Low Leakage < 5.0 μA
- These are Pb−Free Devices

Mechanical Characteristics:

CASE: Void-free, Transfer-molded, Thermosetting Plastic Epoxy Meets UL 94, V−0

LEAD FINISH: 100% Matte Sn (Tin)

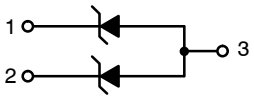
MOUNTING POSITION: Any

QUALIFIED MAX REFLOW TEMPERATURE: 260°C Device Meets MSL 1 Requirements

ON Semiconductor®

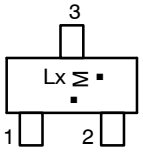
www.onsemi.com

PIN 1. CATHODE
2. CATHODE
3. ANODE



SC−89
CASE 463C
STYLE 4

MARKING DIAGRAM



L	= Device Code
x	= Specific Device
M	= Date Code
▪	= Pb−Free Package

(Note: Microdot may be in either location)

ORDERING INFORMATION

Device	Package	Shipping†
NZL5V6AXV3T1	SC−89*	3000/Tape & Reel
NZL5V6AXV3T1G	SC−89*	3000/Tape & Reel
NZL6V8AXV3T1	SC−89*	3000/Tape & Reel
NZL6V8AXV3T1G	SC−89*	3000/Tape & Reel
NZL6V8AXV3T3G	SC−89*	10000/Tape & Reel
NZL7V5AXV3T1	SC−89*	3000/Tape & Reel
NZL7V5AXV3T1G	SC−89*	3000/Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

*This package is inherently Pb−Free.

DEVICE MARKING INFORMATION

See specific marking information in the device marking column of the table on page 2 of this data sheet.

MAXIMUM RATINGS

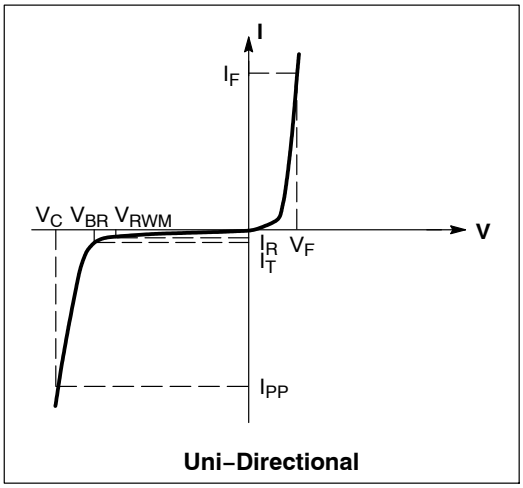
Rating	Symbol	Value	Unit
Total Power Dissipation on FR−5 Board (Note 1) @ T_A = 25°C Derate above 25°C	P_D	240 1.9	mW mW/°C
Thermal Resistance Junction to Ambient	$R_{\theta JA}$	525	°C/W
Junction and Storage Temperature Range	T_J, T_{stg}	−55 to +150	°C
Lead Solder Temperature − Maximum (10 Second Duration)	T_L	260	°C
IEC61000−4−2 (Contact)		10	kV

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.
1. FR−5 board with minimum recommended mounting pad.
*Other voltages may be available upon request.

ELECTRICAL CHARACTERISTICS

(T_A = 25°C unless otherwise noted)
UNIDIRECTIONAL (Circuit tied to Pins 1 and 3 or 2 and 3)

Symbol	Parameter
V_{RWM}	Working Peak Reverse Voltage
I_R	Maximum Reverse Leakage Current @ V_{RWM}
V_{BR}	Breakdown Voltage @ I_T
I_T	Test Current
I_F	Forward Current
V_F	Forward Voltage @ I_F



Uni−Directional

ELECTRICAL CHARACTERISTICS (T_A = 25°C unless otherwise noted, V_F = 0.9 V Max @ I_F = 10 mA for all types)
UNIDIRECTIONAL (Circuit tied to Pins 1 and 3 or Pins 2 and 3)

Device	Device Marking	V_{RWM}	I_R @ V_{RWM}	Breakdown Voltage				Surge			
				V_{BR} (Note 2) (V)			@ Iz_T	V_C (V) @ I_{PP} = 1.0 A†	V_C (V) @ Max I_{PP}†	Max I_{PP} (A)†	P_{pk} (W)†
		V	μA	Min	Nom	Max	mA	Typ	Max		Typ
NZL5V6AXV3T1	L0	3.0	5.0	5.32	5.6	5.88	5.0	7.0	10.1	4.8	50
NZL6V8AXV3T1	L2	4.5	1.0	6.46	6.8	7.14	5.0	7.9	11.9	6.7	73
NZL6V8AXV3T3	L2	4.5	1.0	6.46	6.8	7.14	5.0	7.9	11.9	6.7	73
NZL7V5AXV3T1	L3	5.0	1.0	7.12	7.5	7.88	5.0	8.8	13.5	5.7	75

2. V_{BR} measured at pulse test current I_T at an ambient temperature of 25°C.
† Surge current waveform per Figure 5.

TYPICAL CHARACTERISTICS

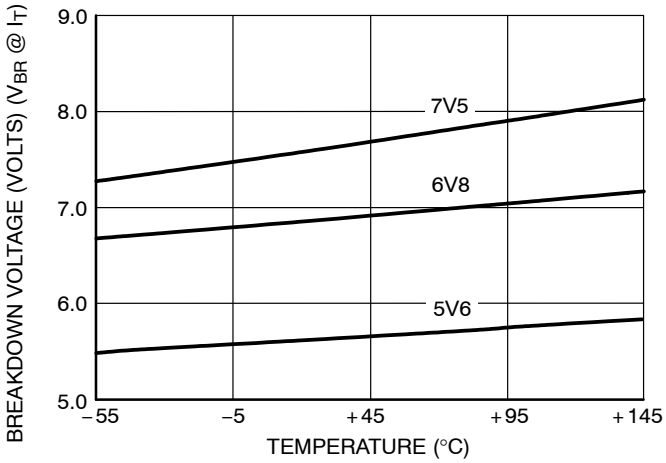


Figure 1. Typical Breakdown Voltage versus Temperature

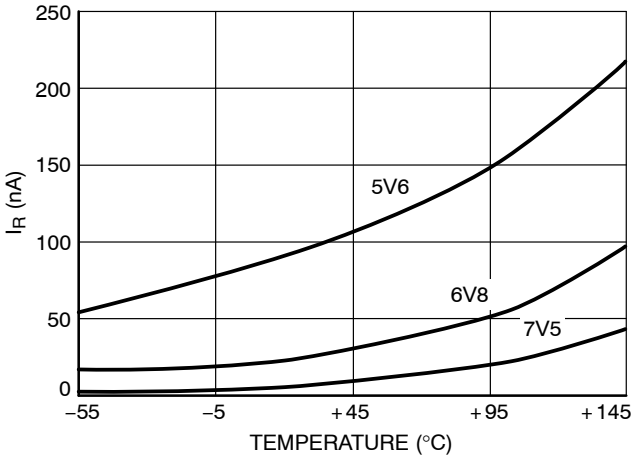


Figure 2. Typical Leakage Current versus Temperature

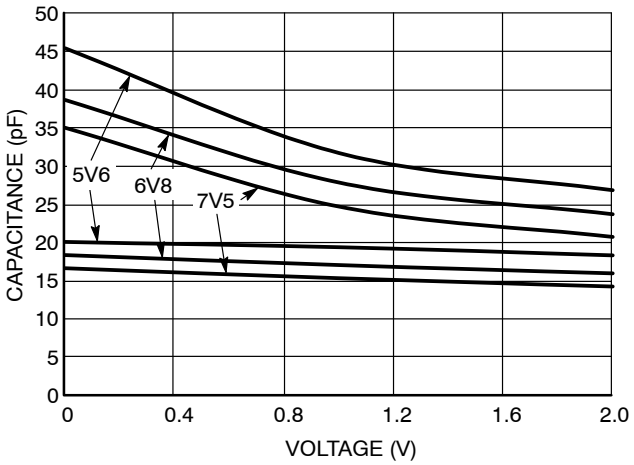


Figure 3. Typical Capacitance versus Bias Voltage
(Upper curve for each part is unidirectional mode, lower curve is bidirectional mode)

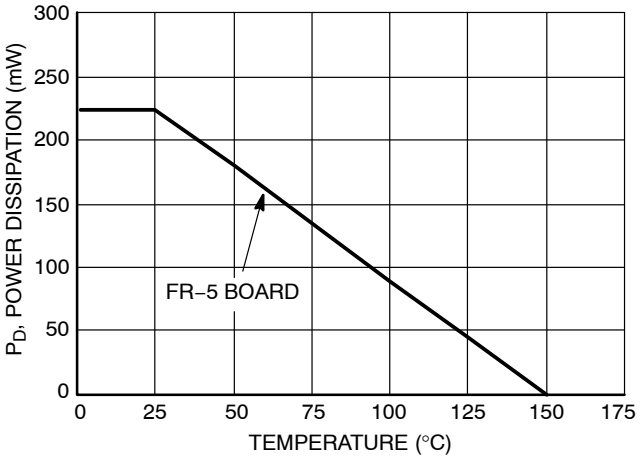


Figure 4. Steady State Power Derating Curve

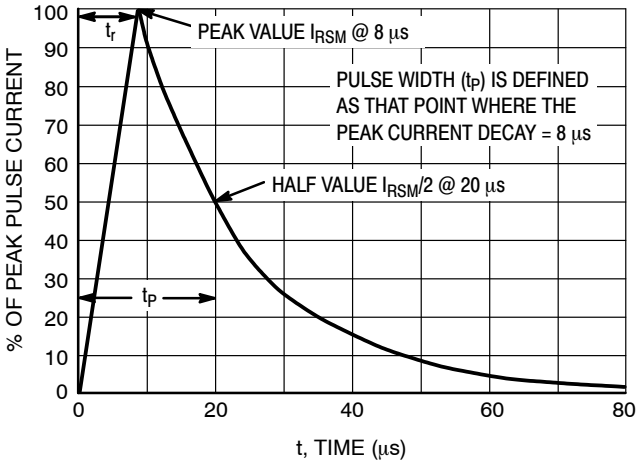


Figure 5. 8 x 20 μs Pulse Waveform

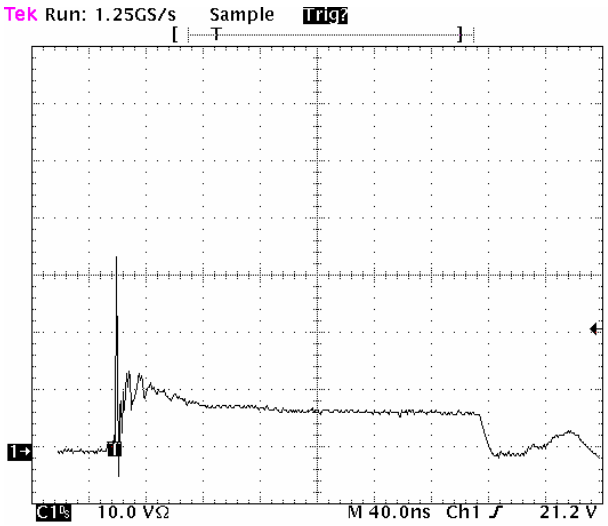


Figure 6. Positive 8 kV contact per IEC 6100−4−2 − NZL6V8AXV3T1G

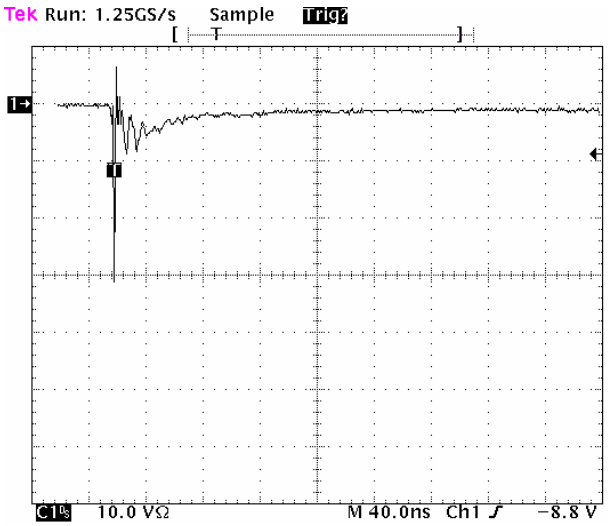


Figure 7. Negative 8 kV contact per IEC 6100−4−2 − NZL6V8AXV3T1G

TYPICAL COMMON ANODE APPLICATIONS

A dual junction common anode design in an SC−89 package protects two separate lines using only one package. This adds flexibility and creativity to PCB design especially when board space is at a premium. Two simplified examples of surge protection applications are illustrated below.

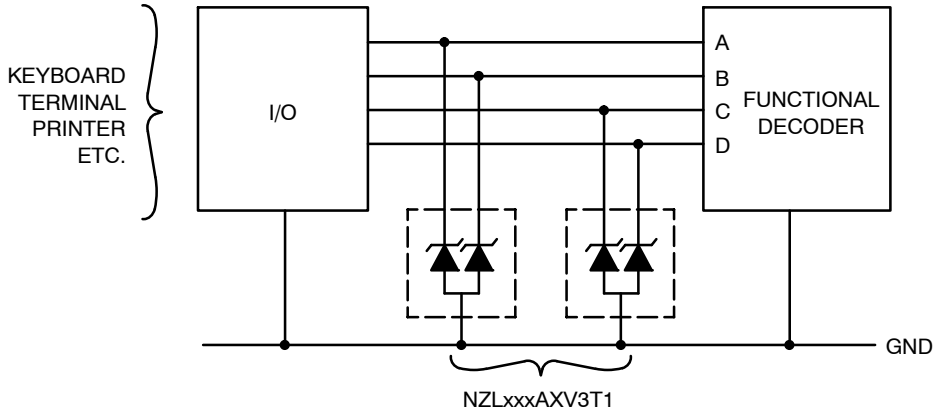


Figure 8. Computer Interface Protection

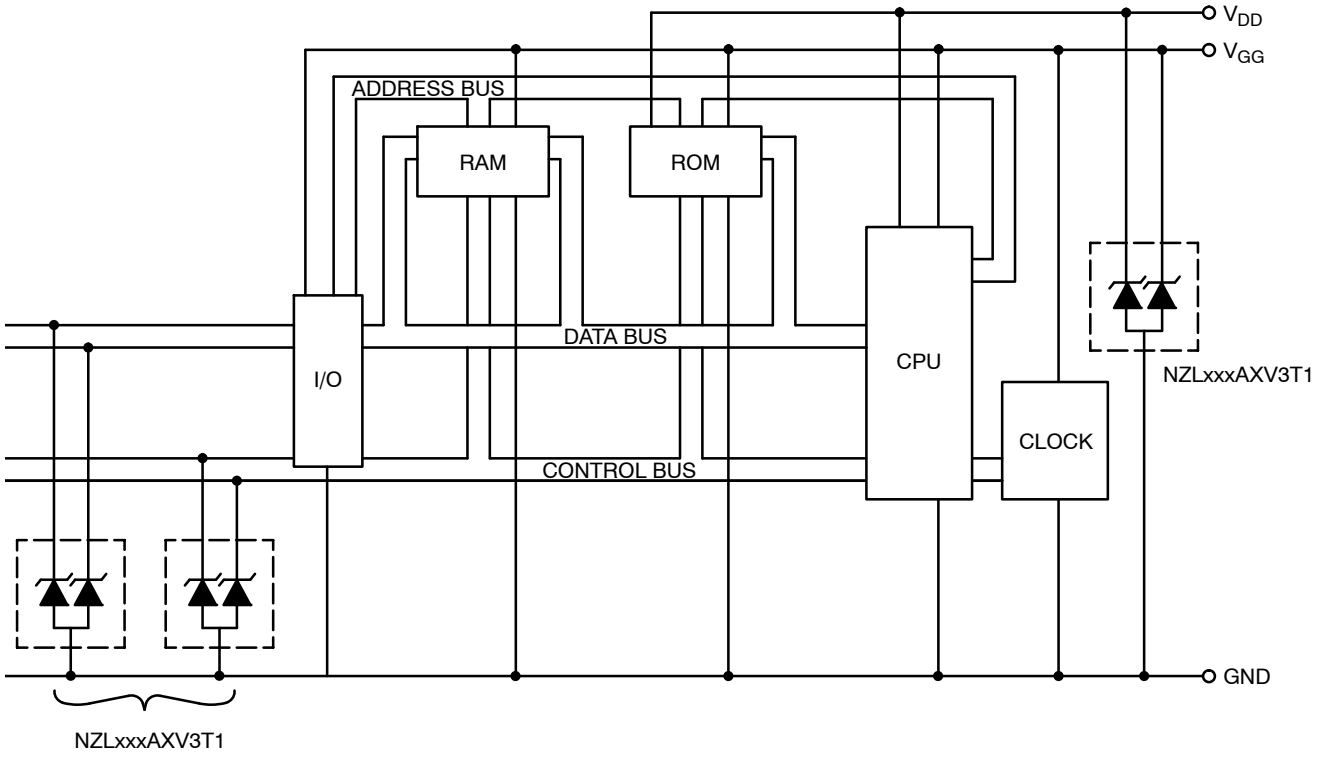
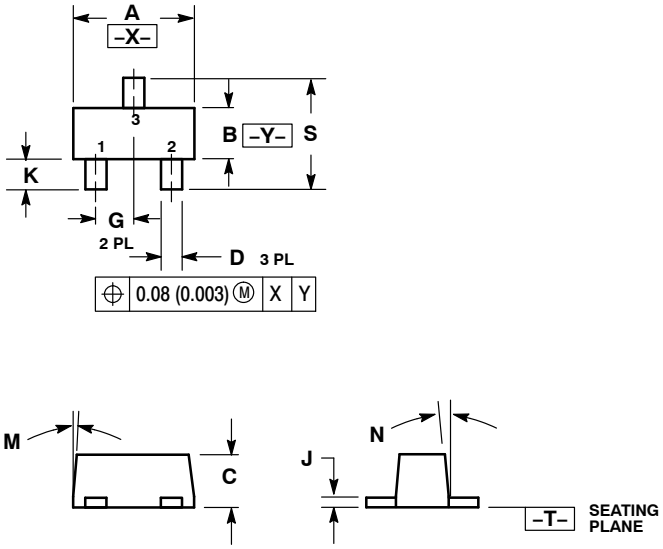


Figure 9. Microprocessor Protection

PACKAGE DIMENSIONS

SC−89, 3−LEAD
CASE 463C−03
ISSUE C

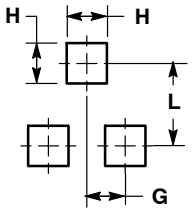


NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETERS
3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.
4. 463C−01 OBSOLETE, NEW STANDARD 463C−02.

	MILLIMETERS			INCHES		
DIM	MIN	NOM	MAX	MIN	NOM	MAX
A	1.50	1.60	1.70	0.059	0.063	0.067
B	0.75	0.85	0.95	0.030	0.034	0.040
C	0.60	0.70	0.80	0.024	0.028	0.031
D	0.23	0.28	0.33	0.009	0.011	0.013
G		0.50 BSC			0.020 BSC	
H		0.53 REF			0.021 REF	
J	0.10	0.15	0.20	0.004	0.006	0.008
K	0.30	0.40	0.50	0.012	0.016	0.020
L		1.10 REF			0.043 REF	
M	---	---	10	---	---	10
N	---	---	10	---	---	10
S	1.50	1.60	1.70	0.059	0.063	0.067

STYLE 4:
PIN 1. CATHODE
2. CATHODE
3. ANODE

SOLDERING FOOTPRINT



RECOMMENDED PATTERN OF SOLDER PADS

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT:
Literature Distribution Center for ON Semiconductor
19521 E. 32nd Pkwy, Aurora, Colorado 80011 USA
Phone: 303−675−2175 or 800−344−3860 Toll Free USA/Canada
Fax: 303−675−2176 or 800−344−3867 Toll Free USA/Canada
Email: orderlit@onsemi.com

N. American Technical Support: 800−282−9855 Toll Free USA/Canada
Europe, Middle East and Africa Technical Support:
Phone: 421 33 790 2910
Japan Customer Focus Center
Phone: 81−3−5817−1050

ON Semiconductor Website: **www.onsemi.com**

Order Literature: http://www.onsemi.com/orderlit

For additional information, please contact your local Sales Representative